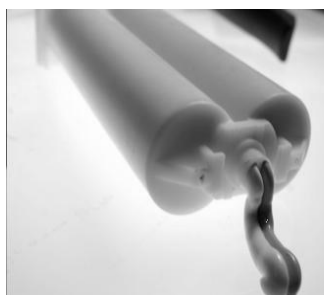


Two part thermal gel pad / XK-S20

Features:

- 1:1 mix
- (no cure by-product)
- Low stress applications
- Easy to use
- Fast cure by heating



Applications

- Automotive electronics
- Telecommunications
- Computer&peripherals
- Thermally conductive & vibration dampening
- Between any heat-generating semiconductor and a heat sink

	XK-S20	METHOD	UNIT
Color / Part A	White	Visual	
Color / Part B	Yellow	Visual	
Features	Soft gel	-	-
Density	2.2	ASTM D792	g/cm3

Before Cured Property

A:B	1:1	-	-
Mixed Viscosity (20rpm)	320	ASTM D2196	Pa.s
Shelf Life @ 25°C	6		month

After Cured Property

Color	Yellow	Visual	-
Cure Schedule 1	6hr/25°C		
Cure Schedule 2	40 min/80°C		
Cure Schedule 3	10 min/100°C		
Working time	120 min/25°C		
Hardness	Shore00 60	ASTM D2240	
	AskerC 30	JIS K7312	
Tensile Strength.	0.3	ASTM D412	Mpa
Elongation	>50	ASTM D412	%
Continuous Use Temp	-40~150		°C

Electrical Property

Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	>10 ¹²	ASTM D257	Ohm-cm
Dielectric Constant	5	ASTM D150	(1KHz)
Flame Rating	V-0	UL94	

Thermal Property

Thermal Conductivity	2.0	ASTM D5470	W/m*K
Heat Capacity	1	ASTM E1269	J/g-K